ABSTRACT

Disclosed in the present invention is a lifting method for wafer drying, the method comprising the following steps: a wafer being located below a liquid level, supporting mechanisms driving the wafer to ascend, wherein the ascending speed of each supporting mechanism is V1, and a lifting mechanism being located below the wafer, but not coming into contact with the wafer, wherein the ascending speed of the lifting mechanism is V2, such that $V2 \leq V1$; the top of the wafer approaching the liquid level, the supporting mechanisms separating from the wafer while maintaining the ascending state of the wafer, and the lifting mechanism ascending to come into contact with the wafer, so as to continue to push the wafer upwards to extend beyond the liquid level; and the wafer being driven by the lifting mechanism to continue to ascend until the wafer completely detaches from the liquid level. In the present invention, the supporting mechanisms on two sides and the lifting mechanism are independently controlled to realize different lifting modes in two stages; in the first half of a lifting process, the wafer is driven by the supporting mechanisms on two sides, such that the wafer contact area is large, allowing the wafer to be stably placed and subjected to a small amount of wear; a holder of the lifting mechanism is not officially involved until the second half of the wafer lifting process, such that operating time of the holder for each wafer is halved, resulting in a lower amount of wear and a longer service life; and there is no need to replace the holder frequently.

FIG. 16